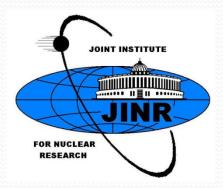
Results of measuring GaAs sensor planes

U.Kruchonak, V. Elkin, O.Novgorodova

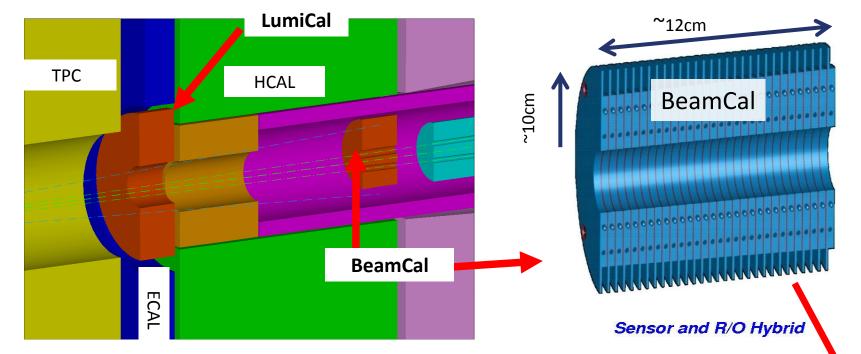






21-st FCAL collaboration meeting

The Beam Calorimeter - BeamCal



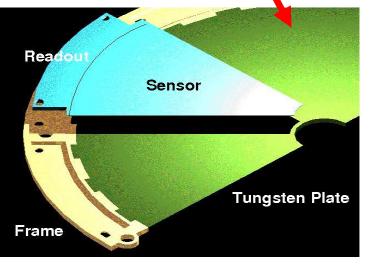
Compact EM calorimeter with sandwich structure:

30 layers of 1 X₀

o3.5mm W absorber and 0.3mm radiation hard sensor

- Angular coverage from 5mrad to 28 mrad (6.0 > $|\eta|$ > 4.3)
- ♦ Moliére radius $R_M \approx 1$ cm
- \clubsuit Segmentation between 0.5 and 0.8 x $\rm R_{M}$

GaAs:Cr is offered as a radiation hard sensor for Beamcal.



The main characteristics of semiconductor

materials

Material	Densit y,	Atomic number	Band gap,	μτ product, cm²/V	
	g/cm ⁻³	number	eV	μ _n τ _n	μ _ρ τ _ρ
Si	2.33	14	1.12	~ 1	~ 1
GaAs	5.32	~ 32	1.43	~ 10 ⁻⁴	~ 10 ⁻⁵
CdTe	5.85	~ 49	1.5	10 ⁻³	10 ⁻⁴
Hgl ₂	6.4	~ 81	2.13	10-4	10 ⁻⁵
Pbl ₂	6.16	~ 83	2.32	10 ⁻⁵	10 ⁻⁶

We can see that the pure (not doped) Si has the charge carriers lifetime which exceeds the lifetime for binary semiconductors by 4 orders. However, pure semiconductors (Si) have not sufficient radiation hardness and relatively small conversion efficiency for γ .

GaAs:Cr Sensor Plane

Produced by the Siberian Institute of Technology, Tomsk
 semi-insulating GaAs doped by Sn (shallow donor)
 compensated by Cr (deep acceptor): to compensate
 electron trapping centers EL2+ and provide i-type
 conductivity.

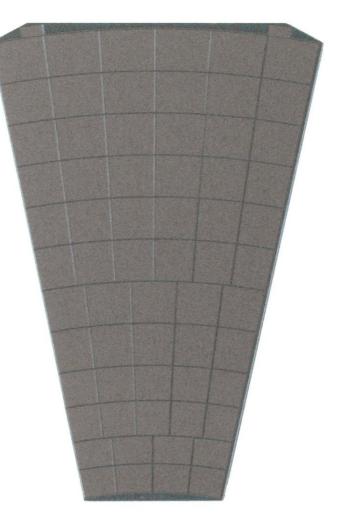
Due to a wider band gap these samples are radiation harder and have a lower leakage current (resistivity >10⁹ Ohm*sm)

BUT....

Due to small holes mobility only electron charge can be collected. It limits maximum CCE to 50% for minimum ionising particles.

GaAs:Cr Sensor Plane

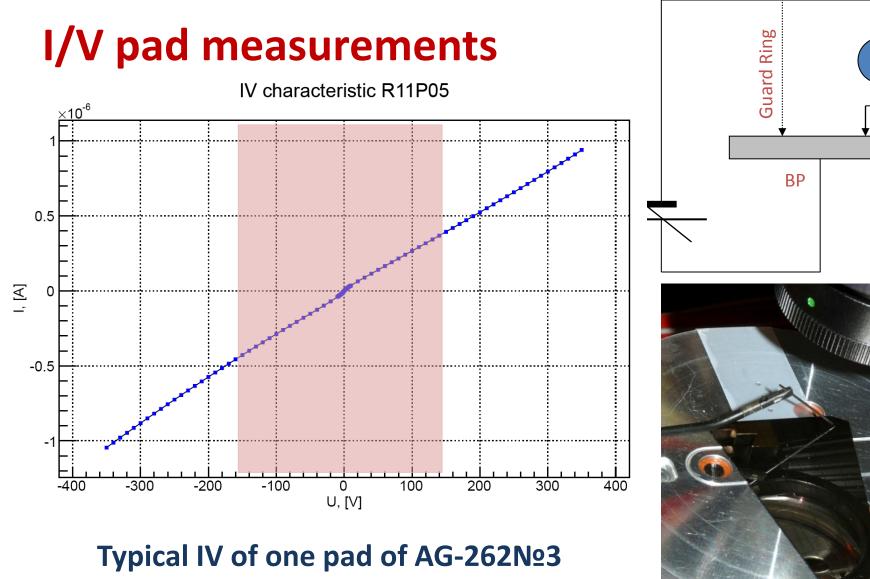
- New set of 11 sector size GaAs sensors (22 at all)
- Thickness 500 μm
- Metallization ~1 µm Ni both sides
- 12 rings
- 64 pads from 18 to 42 mm²
- Surrounded by 120 µm width guard ring



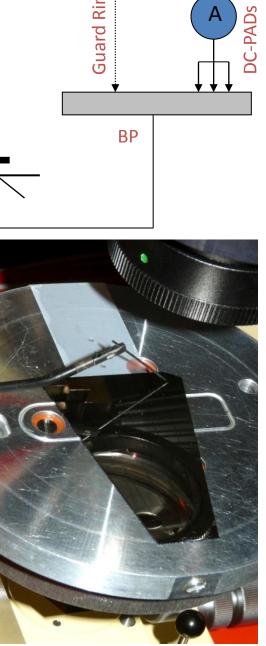
GaAs:Cr Sensor producer data

Nº	Detector	thickness, um	collected charge, e*	metallization, Type of metallization	
				pixels	Guard ring
1	AG-262 №1	506	40570	Ni	Ni
2	AG-262 №3	512	41640	Ni	Ni
3	AG-262 №4	509	42690	Ni	Ni
4	AG-221 №6	498	37020	Ni	Ni
5	AG-262 №12	504	35630	Ni	Ni
6	AG-262 №13	517	37580	Ni	Ni
7	AG-262 №15	518	39190	Ni	Ni
8	AG-262 №16	509	37170	Ni	Ni
9	AG-262 №19	507	34490	Ni	Ni
10	AG 84 № 23	492	37930	Ni	Ni
11	AG 84 №24	485	38520	Ni	Ni

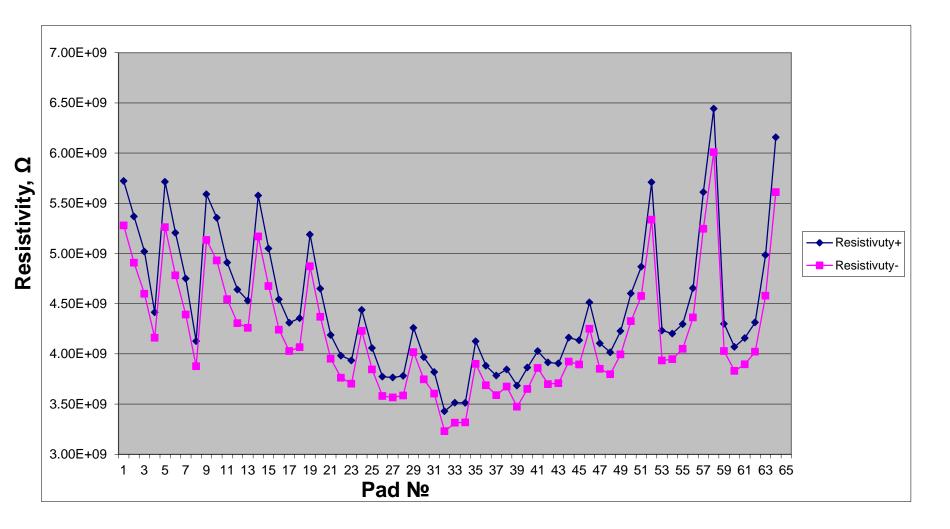
* - U_{bias}= -150V, RT, β - radiation (⁹⁰Sr, mip).



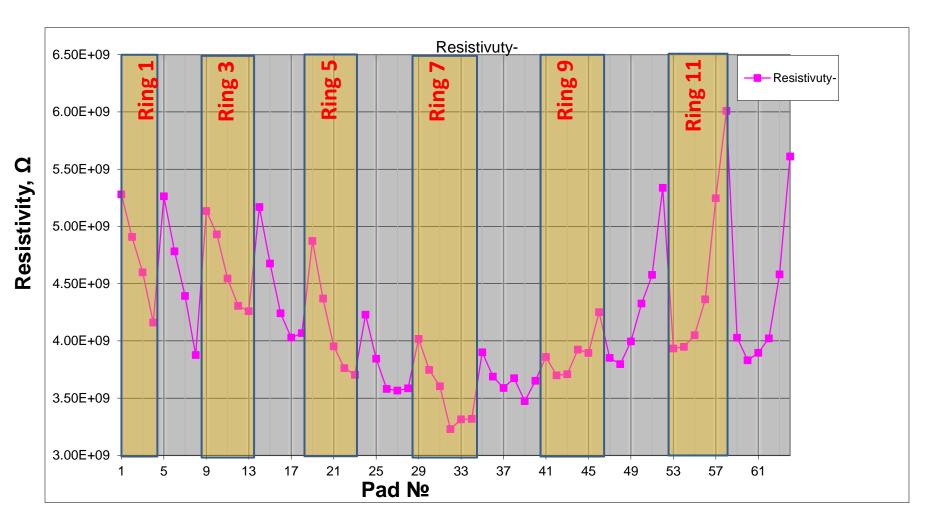
• symmetric in the range +/-350V •linear in the range +/-150V



Resistivity pads distribution of AG221Nº6

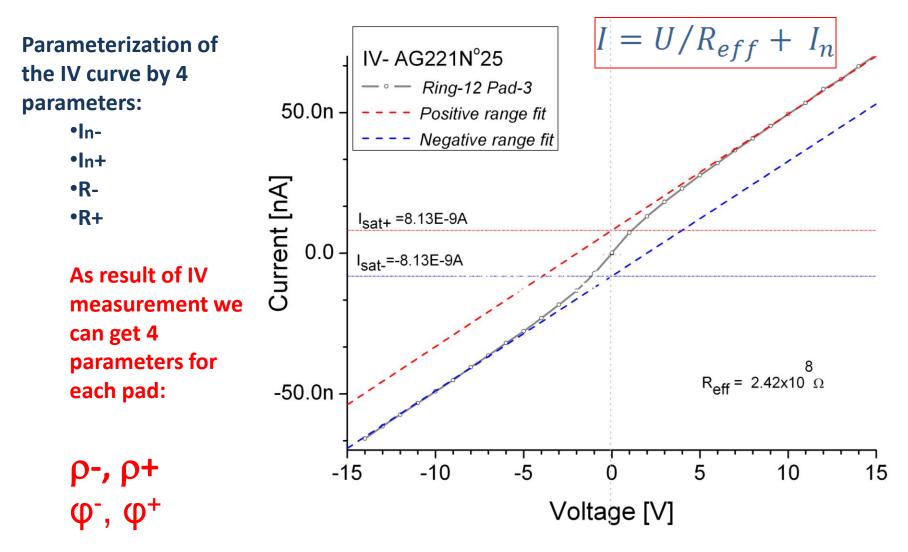


Resistivity pads distribution of AG221Nº6



It was found that for some sensors the ρ -, ρ ⁻ strongly depends on Ring N^o

I-V in range +/-10V



Measurement of the barrier height on border of metal-*semiinsulating* gallium arsenide

total current through the device

 $I = U/R_{eff} + I_n$

Reff - effective resistance of the entire device

In or *Isat* - Saturation current - Limiting current from metal to semiconductor

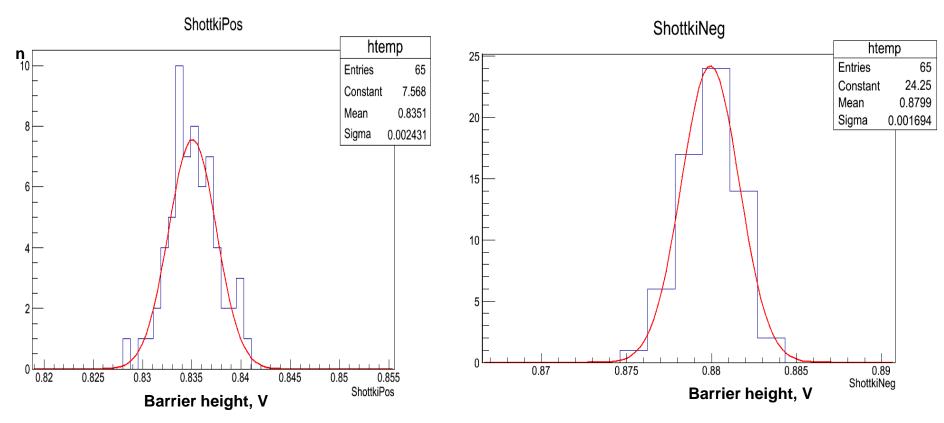
$$I_n = SA_n^* T^2 \exp\left(-\frac{q\varphi_{Bn}}{kT}\right)$$
[1]

S-Cross-sectional area, $A_n^* = 8.16 A^* cm^{-2} * K^{-2}$ - Richardson constant for GaAs

T - Temperature of device, **q** - electron charge, **k** - Boltzmann constant

 ψ_{Bn} - barrier height on border of metal-semiinsulating gallium arsenide

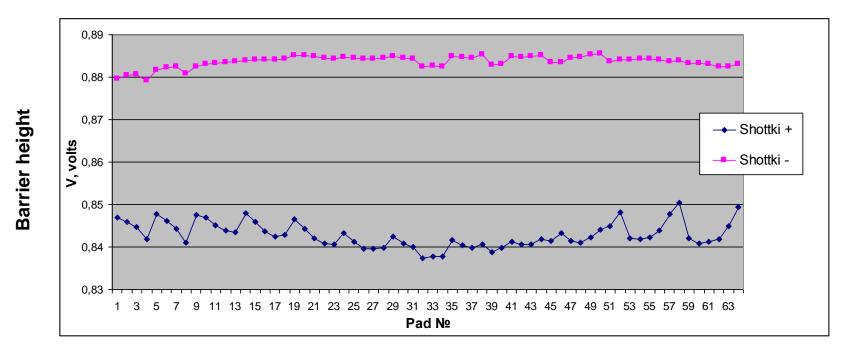
Shottky barrier height distribution of AG221N06



The Schottky barrier height is measured for both polarities. Positive branch corresponds to the barrier on the border Pad-GaAs, negative corresponds to the barrier on the border Backplane-GaAs.

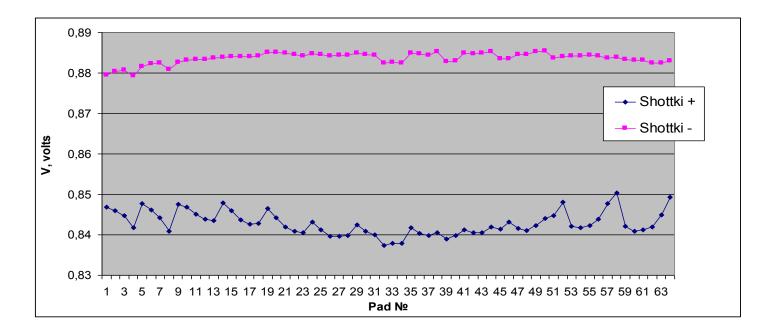
Previously measured and published value for contact based on vanadium **0.81 ±0.02V** [1]

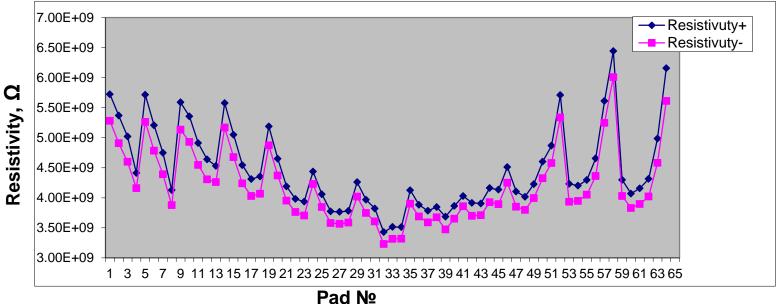
Barrier height distribution of AG221Nº6



The sensors with ρ^+ , ρ^- dependence on Ring N^o have similar behavior for ϕ^+ , but not for ϕ^-

Barrier height distribution of AG221Nº6





Barrier height

Average resistivity and barrier height of 11 sensors

N⁰	Detector	Thickness, um	Resistivity, Ohm*cm		Barrier height, volts	
			ρ+	ρ-	φ+	φ-
1	AG-262 №1	506	3,27E+009	3,05E+009	0,835	0,880
2	AG-262 №3	512	3,10E+009	2,90E+009	0,835	0,880
3	AG-262 №4	509	3,25E+009	3,09E+009	0,837	0,884
4	AG-221 №6	498	4,47E+009	4,19E+009	0,843	0,884
5	AG-262 №12	504	3,38E+009	3,26E+009	0,838	0,884
6	AG-262 №13	517	2,72E+009	2,58E+009	0,833	0,883
7	AG-262 №15	518	3,22E+009	3,06E+009	0,837	0,884
8	AG-262 №16	509	3,63E+009	3,49E+009	0,839	0,885
9	AG-262 №19	507	3,25E+009	3,08E+009	0,836	0,884
10	AG 84 № 23	492	2,92E+009	2,78E+009	0,833	0,880
11	AG 84 №24	485	3,08E+009	2,93E+009	0,834	0,881
Average ± Sigma			3,30±0,45 E+09	3,13±0,43 E+09	0,836±0,003	0,883±0,002

Defects found

The criteria for a pad accepted as good:

ρ> 10e9 Ω*cm

Some pads or guard rings have untypical behavior.

8 of 22 sensors have deflection Guard ring and one pad: that may be related internal structure injury. It appear on the crystal boundary for all cases.

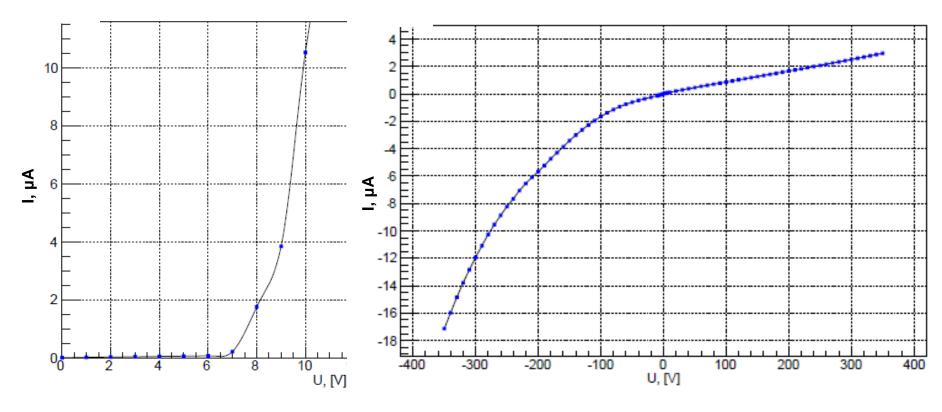
All 8 sensors are made of the same crystal AG84!

Unusual pads

Guard ring +

Ring1-Pad4; Ring12-Pad1; Ring12-Pad6;

Untypical IV behavior



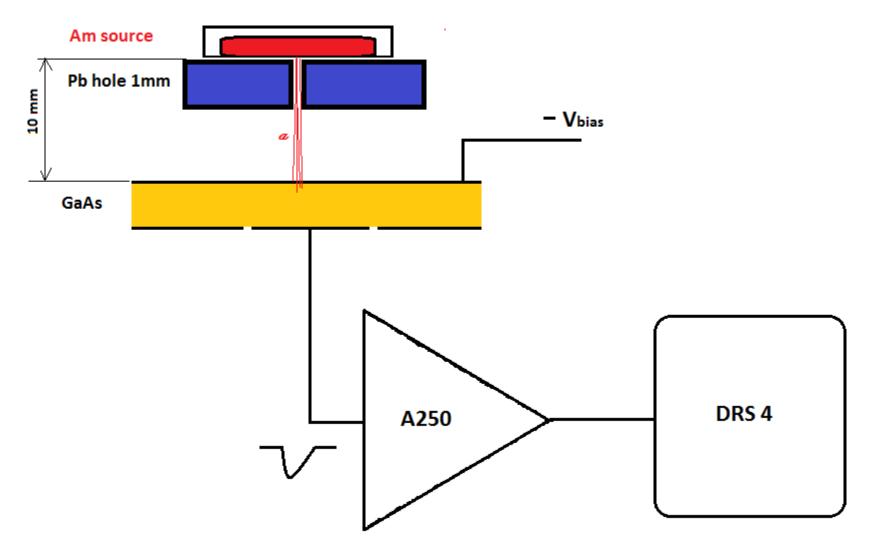
Ag84N24 Guard ring

Ag84N23 Ring 1 Pad 4

8 of 22 planes have 1 unusual pad and GR (All 8 of 12 ¢ AG84)

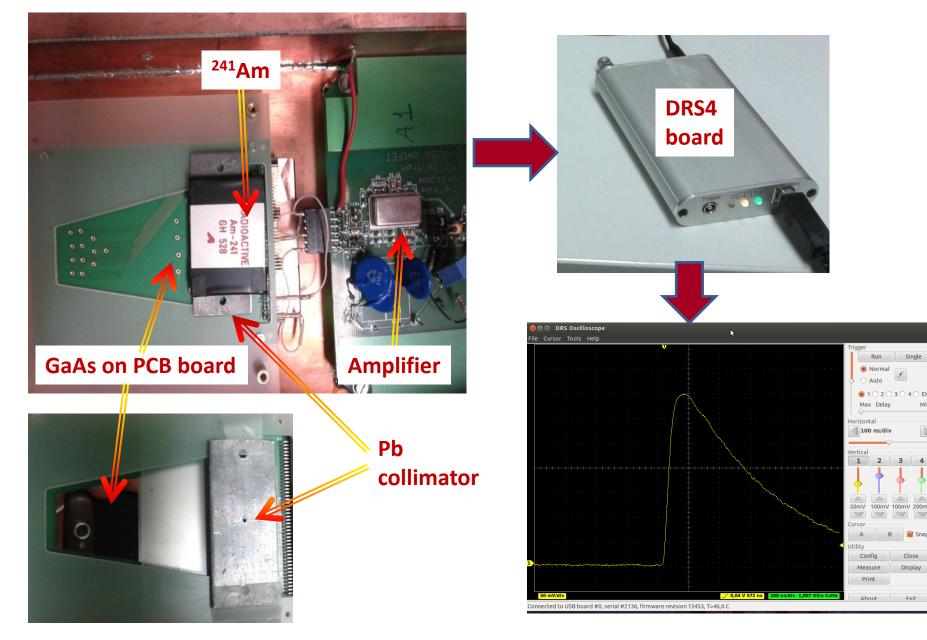
N°	Pad N°	Breakdown voltage, V
AsGa84N7	Guard ring	-330
AsGa84N7	Ring12-Pad1	-310
AsGa84N13	Guard ring	-160; +200
AsGa84N13	Ring12-Pad6	-280
AsGa84N21	Guard ring	+30
AsGa84N21	Ring1-Pad4	+50
AsGa84N26	Guard ring	-110; +230
AsGa84N26	Ring12-Pad1	-210
AsGa84N28	Guard ring	-300
AsGa84N28	Ring12-Pad6	+330
AsGa84N41	Guard ring	+110
AsGa84N41	Ring12-Pad6	+110
AsGa84N23	Guard ring	ρ- < 1E08
AsGa84N23	Ring1-Pad4	ρ- < 1E08
AsGa84N24	Guard ring	+10
AsGa84N24	Ring1-Pad4	+10
AsGa84N24	Ring12-Pad6	+30

α-spectra ²⁴¹Am experimental setup.



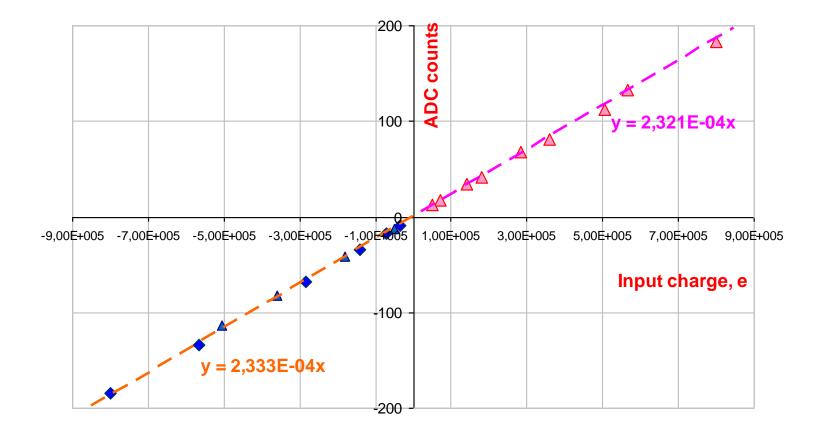
Sensor **AG84N13** has several bonded pads, Ring 12 Pad 3 was connected for measurement.

α -spectra of ²⁴¹Am experimental setup.



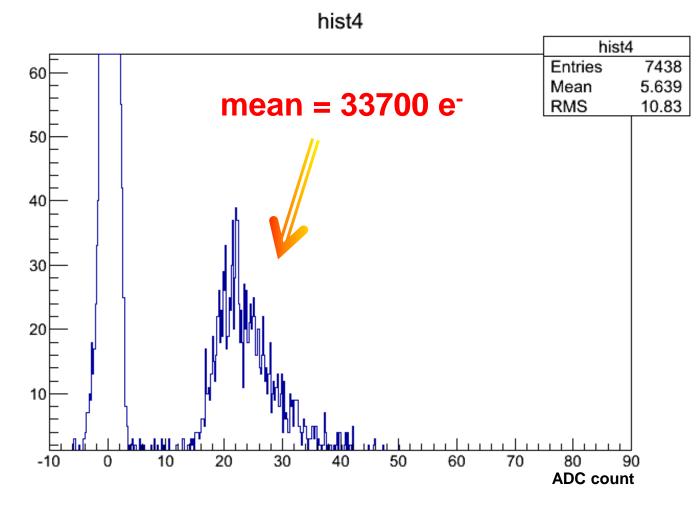
EX

Amplifier & readout calibration.



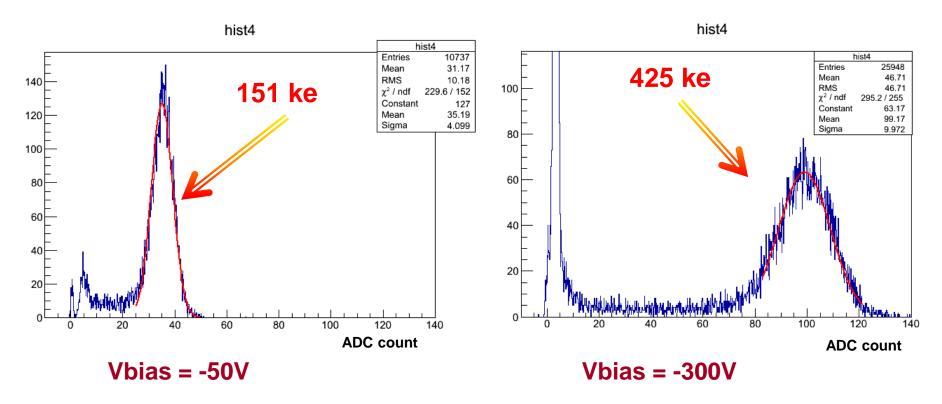
For both positive and negative signal polarity calibration gives same value: $1count = 4,29E03 e^{-1}$

MIP -spectrum of ⁹⁰Sr



Sr MIP measured with Vbias = -400V gives the signal 33700 MIP produces ~150 e/h pairs per 1um, it corresponds CCE ~ 45% or 90 % for electron collection only.

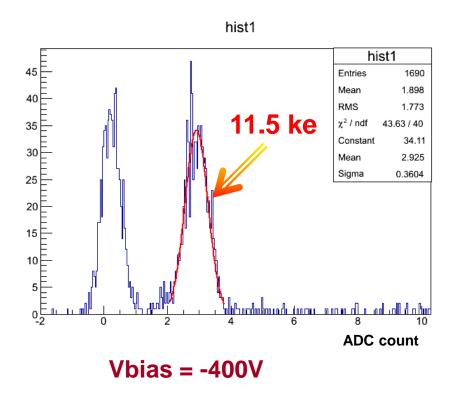
α -spectra of ²⁴¹Am

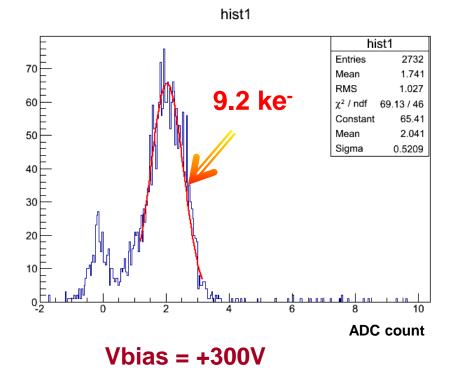


Am from BP, Vth = 10mV, Gauss fit.

Signal from α is rising with V_{bias}, but Signal/Sigma rate is not so critical: 8.8 for -50V, 9.9 for -300V.

α -spectra of ²⁴¹Am



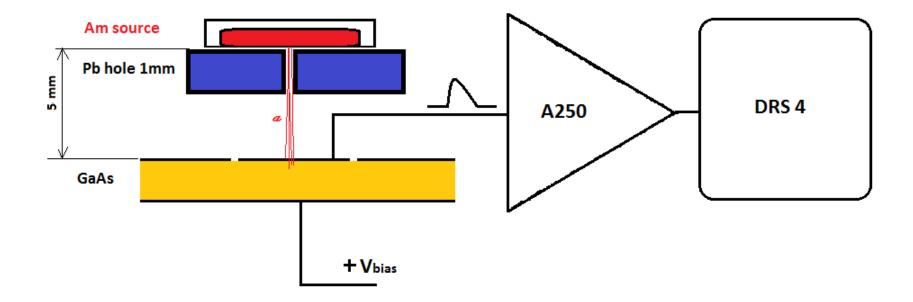


Am source closed by the 50um Cu foil to kill alpha. All big signals escaped and rate dropped from 300Hz to ~2Hz. About 12ke signal may be part of Am 60keV.

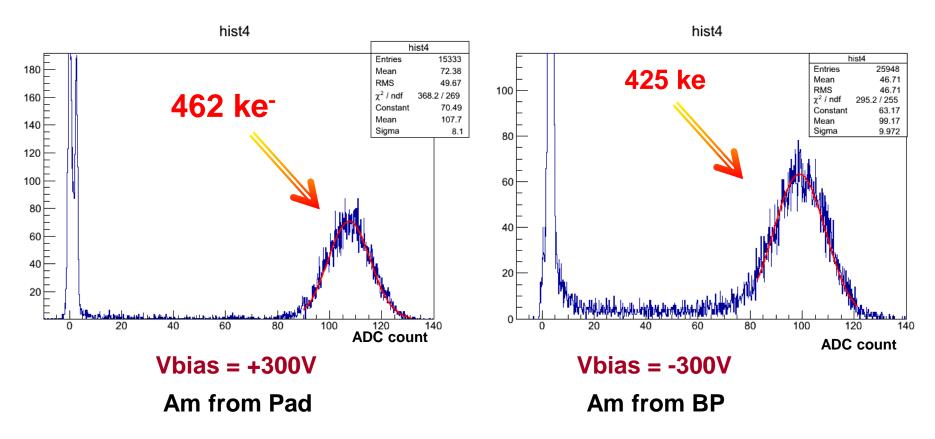
Reversing Vbias = +300V gives only 9.8 ke signal mean and rate dropped from 300Hz to ~6 Hz.

It proves only electron charge collection for GaAs:Cr.

α -spectra of ²⁴¹Am from Pad.



α -spectra of ²⁴¹Am

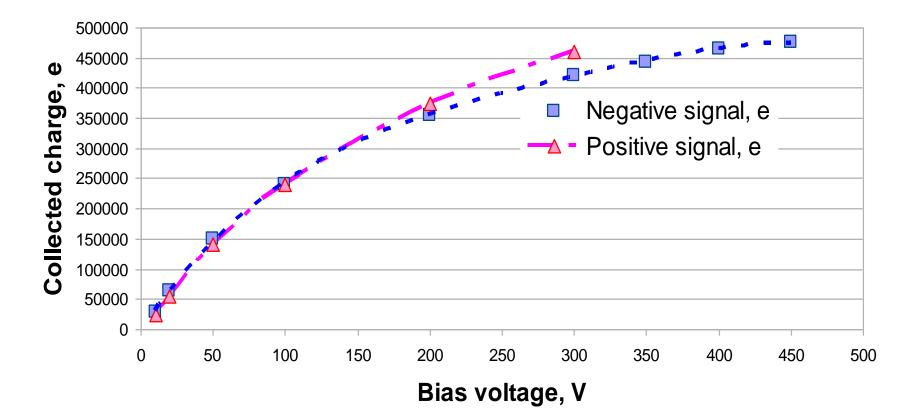


When α comes from pad, the signal a bit higher(8% for V_{bias} =300V), Also signal/noise ratio is better : 13 vs 10.

This can be explained by the fact that the distance from the source to the pad was in the first case 5mm, the second 10 mm.

α-spectra of ²⁴¹Am charge collection vs V_{bias}

AG84N13 Ring 12 Pad 3



Charge collection was measured at different V_{bias} up to 1V/um. There is a tendency to saturation.

For the positive V_{bias} is limited to 310V due to noise.

Summary

DESY's experimental set-up has been applied for measurement of I/V and temperature dependence of GaAs sector sensors (I-V, ρ , φ_{Bn})

The results are:

✓ I-V of 11 new sensors was measured

✓ I-V behavior is well consistent with previous results and theoretical calculations.
✓ The resistivity and the barrier heigh on the border metal-semiinsulating GaAs was measured for all pads.

✓ Together with previous measurements now all 22 sector size sensors are certified:

14 were recognized as completely good,

for all pad ρ >10e9 GOhm*cm, 0.8V< ϕ_{Bn} < 0.9 V.

7 has defects the current exceed the limit for one polarity in Guard ring and one pad. 1 sensor has GR resistivity ~ 10e08 for negative polarity.

 $\checkmark \alpha$ -spectra of ²⁴¹Am were measured for different Bias voltages, polarity, geometry.

✓ only electron charge collection approved.

✓ collected charge slightly depends on the bias voltage polarity, but strongly depends on ist value and the interaction depth in the detector.

We have all 22 sensors tested.

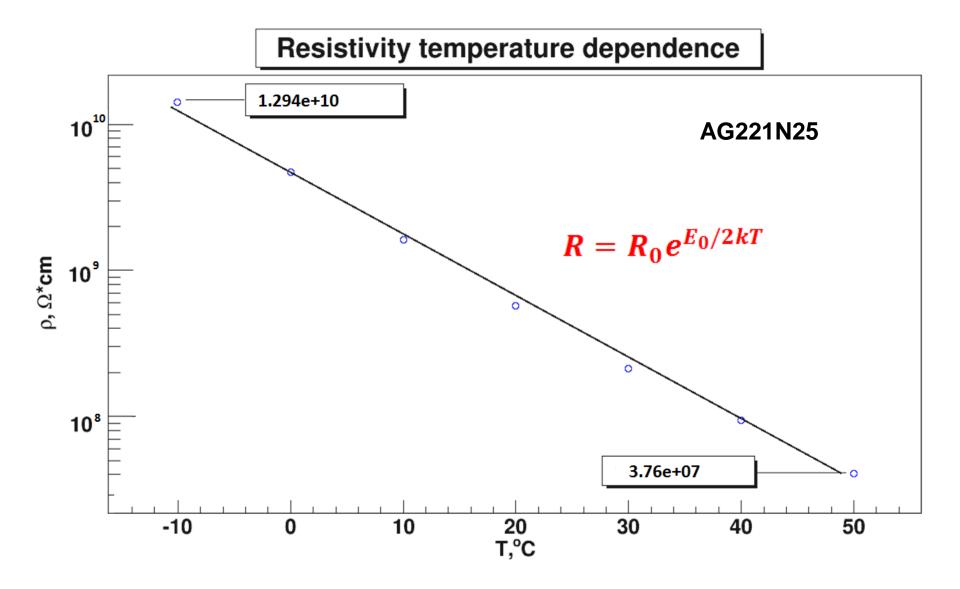
References

- **1. Measurement of the barrier height on border of metal-semiinsulating gallium arsenide.** *G.I. Ayzenshtat, M.A. Lelekov, O.P. Tolbanov. Физика и техника полупроводников , 2007, том 41, вып. 11*
- 2. Current transport in gallium arsenide detector compensated by chromium

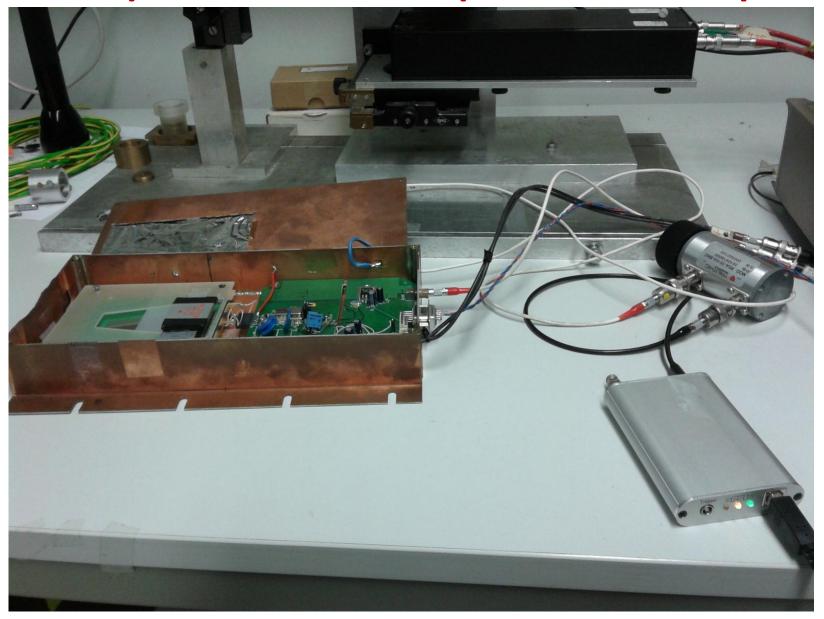
G.I. Ayzenshtat, M.A. Lelekov, V.A. Novikov, L.S. Okaevitch, O.P. Tolbanov. Физика и техника полупроводников , 2007, том 41, вып.5

Backup slides

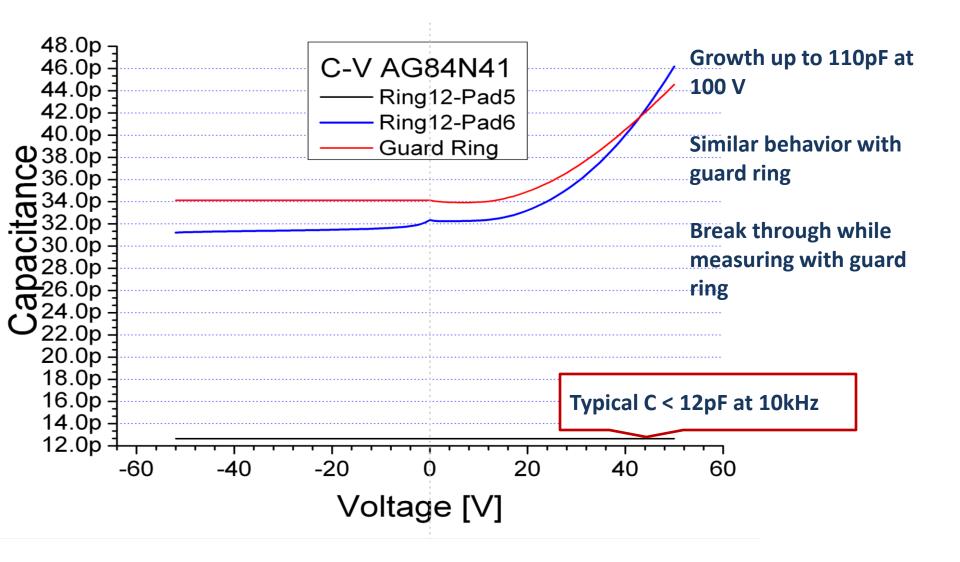
Temperature dependence of the resistivity



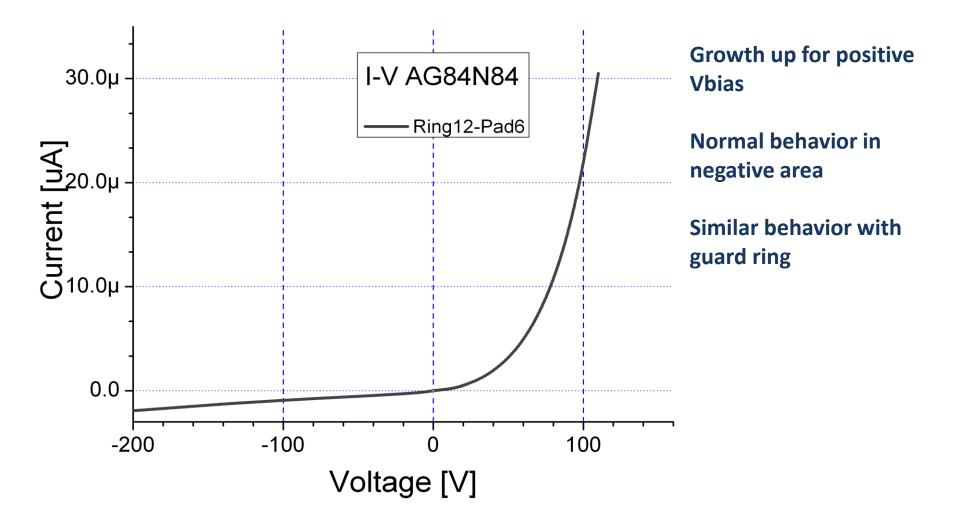
α -spectra of ²⁴¹Am experimental setup.



Unusual pad, unusual guardring and normal pad C-V



Unusual pad I-V



Average resistivity and barrier height of 11 sensors

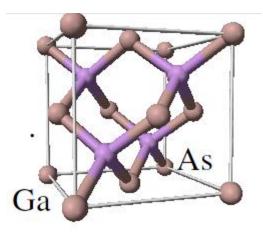
J	N⁰	Detector	thickness, um	Resistivity	ν, Ohm*cm	Darrier height, volts	
				ρ+	ρ-	ϕ^+	φ
	1	AG-84 №13	498	Not processed	Not processed	Not processed	Not processed
	2	AG 84 № 26	502	1.20E9	1.10E9	0.75	0.74
	3	AG 84 № 7	490	2.25E9	2.18E9	0.78	0.79
	4	AG 84 № 19	495	3.00E9	2.79E9	0.78	0.78
	5	AG 84 № 21	492	2.42E9	2.37E9	0.76	0.76
	6	AG 84 № 32	502	3.20E9	3.04E9	0.78	0.77
	7	AG 84 № 39	495	3.71E9	3.48E9	0.79	0.76
	8	AG 84 № 41	487	4.07E9	3.84E9	0.76	0.75
	9	AG 84 № 29	487	3.67E9	3.23E9	0.78	0.81
1	10	AG 84 № 28	500	2.09E9	1.92E9	0.76	0.77
]	11	AG 221 №25	492	2.49E9	2.42E9	0.79	0.81

Forward region of the ILC

Beam calorimeter (BeamCal) - monitor the beam parameters at the interaction point; adjacent to the beampipe.

<u>Luminosity detector (LumiCal)</u> – covers larger polar angles; luminometer of the detector.

<u>The gamma detector (GamCal)</u> – together with BeamCal, measures beamstrahlung photons, which are very collinear to the beam.



Gallium arsenide (GaAs)

Compound semiconductor, direct bandgap Two sublattices of face centered cubic lattice (zinc-blende type)

GaAs grown by Liquid Encapsulated	🛛 Density
Czochralski (LEC).	🛛 Pair cre
doped by Te or Sn (shallow donor)	🔲 Band g
to fill EL2+ trapping centers.	🛛 Electro
Compensated by Cr (deep acceptor) to	🛛 Hole m
high-ohmic intrinsic material.	🛛 Dielecti
Compensation is temperature controlled	🛛 Radiatio
	🖵 Ave. Ede
Semi-insulating - no p-n junction	(by 10 Me
	🛛 Ave. pa
Signal charge transport mainly by electrons	📮 Structu

Structure provided by metallisation (similar to diamond)

Density	5.32 g/cm3
Pair creation E	4.3 eV/pair
Band gap	1.42 eV
Electron mobility	8500 cm2/Vs
Hole mobility	400 cm2/Vs
Dielectric const.	12.85
Radiation length	2.3 cm
🖵 Ave. Edep/100 μm	69.7 keV
(by 10 MeV e-)	
Ave. pairs/100 μm	13000
Structure	p-n or insul